

Title (en)

HOT-STAMPED COMPONENT AND METHOD FOR MANUFACTURING SAME

Title (de)

HEISSGEPRÄGTE KOMPONENTE UND VERFAHREN ZUR HERSTELLUNG DAVON

Title (fr)

COMPOSANT ESTAMPÉ À CHAUD ET PROCÉDÉ DE FABRICATION DE CELUI-CI

Publication

EP 4268986 A1 20231101 (EN)

Application

EP 21915722 A 20211227

Priority

- KR 20200185203 A 20201228
- KR 2021019945 W 20211227

Abstract (en)

According to an aspect of the present disclosure, provided is a method of manufacturing a hot stamping component in which a residual stress analysis value satisfies a preset condition. The method includes heating a blank; forming a molded body by hot stamping the blank; and cooling the molded body to form a hot stamped component. The residual stress analysis value may be a product of a magnitude of an X-ray diffraction analysis (XRD) value obtained by quantifying residual stress by XRD analysis and a magnitude of an electron backscatter diffraction (EBSD) value obtained by quantifying an orientation by EBSD analysis, and the preset condition is about 2.85×10^{-4} Degree²/MPa/μm² or greater and about 0.05 Degree²/MPa/μm² or less.

IPC 8 full level

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CPC (source: EP US)

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